



APPENDIX-A

USING DEVELOPMENT TOOLS

A.1 Programming AT89C51ED2

Following steps should be executed in sequence to program AT89C51ED2 micro-controller.

1. Compile the whole project using Keil uv3 and generate hex file.
2. The hex file can be downloaded (programmed) into AT89C51ED2 using any third party programmer e.g. Crystal Programmer as shown in Figure A-1.
3. Run the P4MIC software and read the hex file into buffer.
4. Go to Device & select the ATMEL AT89C51ED2 controller.
5. Go to Function tab & then click on Auto, which will do all necessary steps automatically & the hex file will be downloaded into micro-controller.



Figure A-1 Crystal Programmer

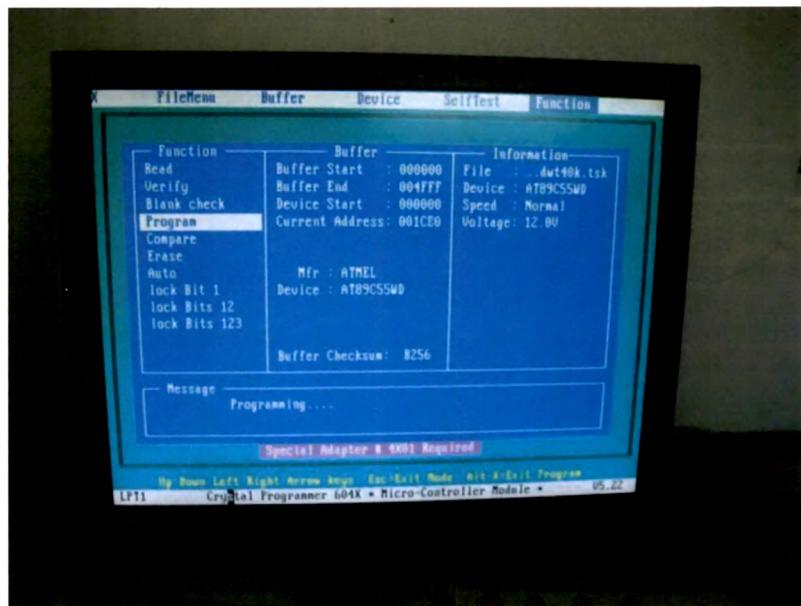


Figure A-2 Programming window

A.2 Keil Real View Project Creation

Follow the steps to create embedded controller project.

1. Open Keil Real View/Keil uv4.
2. Click the New uvision project button to launch the New Project Wizard.
3. Provide name and location for the project as shown in Figure A-3.
4. Choose CPU as NXP LPC2478 and press ok.
5. The start-up file will be automatically loaded.

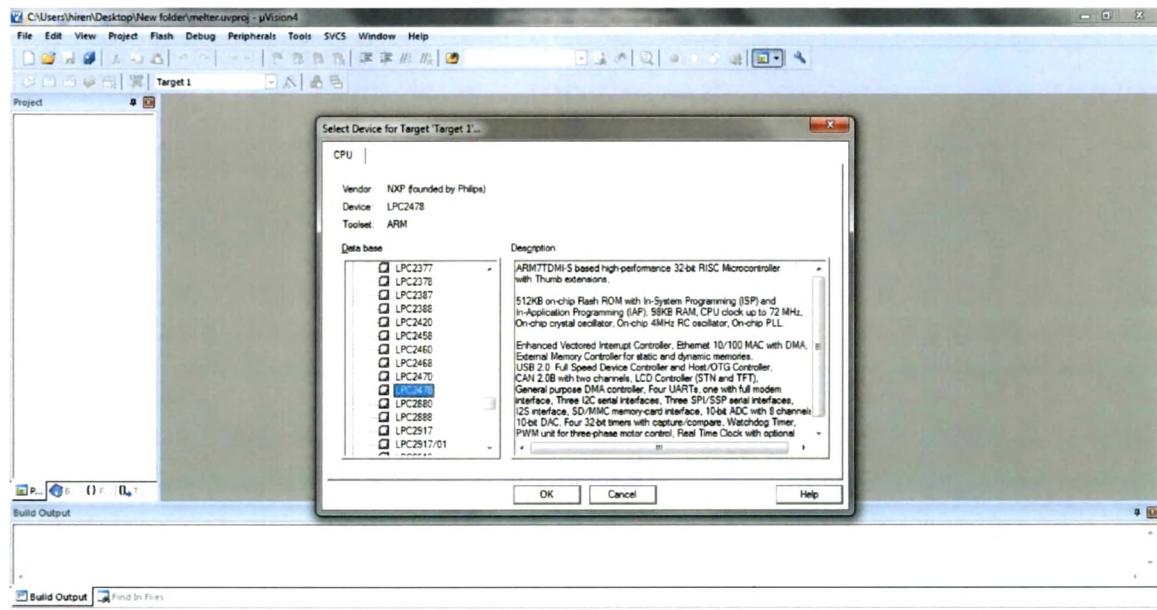


Figure A-3 New Project wizard

6. In Project window double click on LPC2400.S and configure external dynamic & static memory interface by entering into Configuration Wizard as shown in Figure A-4.

Appendix-A

USING DEVELOPMENT TOOLS

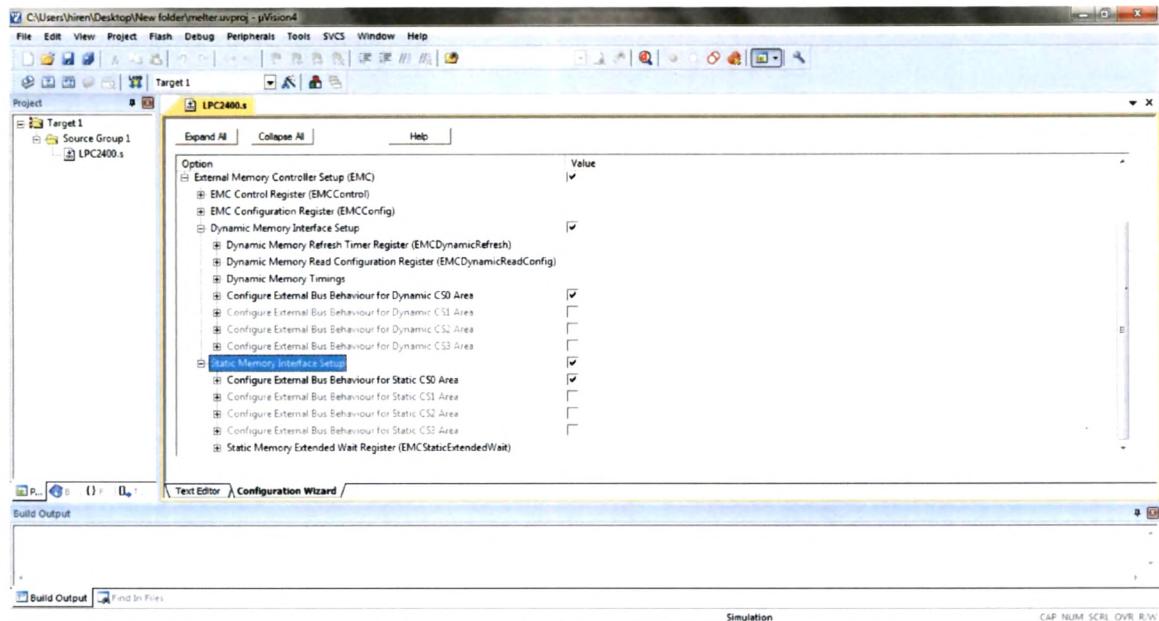


Figure A-4 Configuration wizard

- Add groups as shown in the Figure A-5 and add c files and distribute whole program into different groups & files.

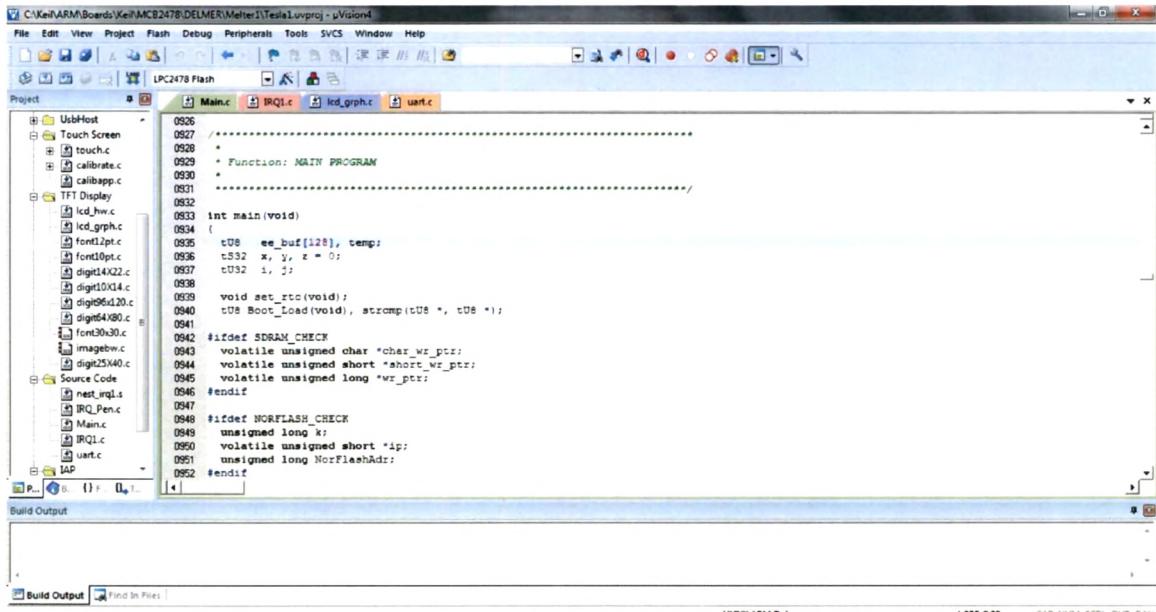


Figure A-5 Project Creation with Different groups

- Once whole project is ready, click on Rebuild All target files button.
- After successfully compiling the project, now it is ready to download and debug the project into actual hardware.
- Connect a ULINK-2 converter between usb-port of PC and the Embedded hardware.
- Press Debug button, the program will be downloaded into hardware & a debug window will open where the program can be executed step by step or the break points can be kept.

A.3 Eagle Schematic Design

Eagle 5.4 can be used to create schematic design & then to create artwork for manufacturing pcb.

Figure A-6 shows the schematic design created in Eagle 5.4.

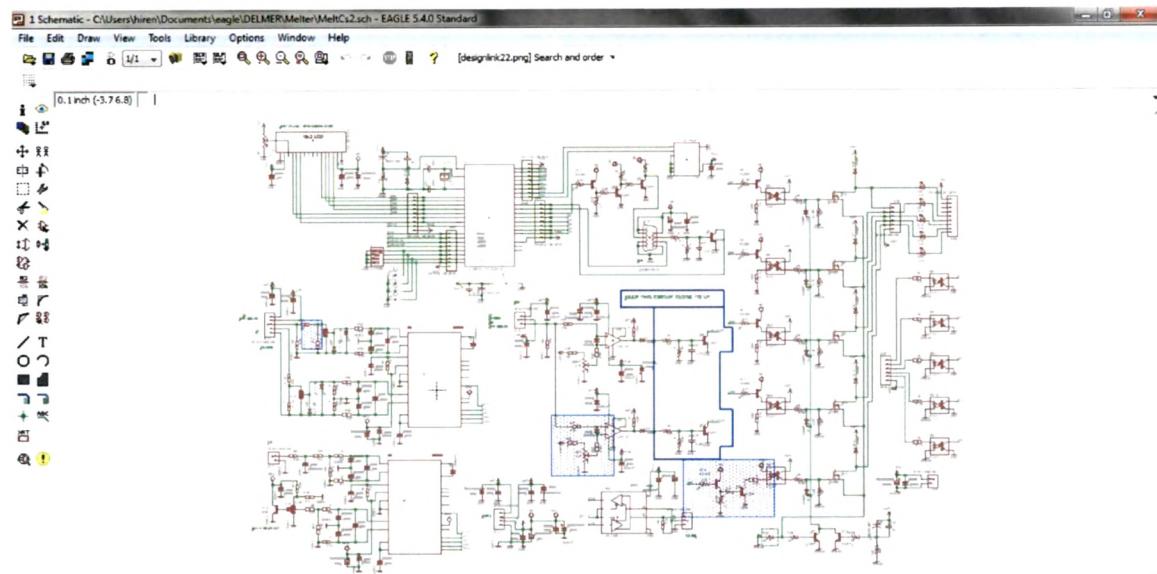
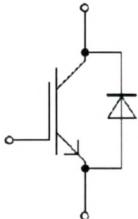


Figure A-6 Schematic Design in Eagle 5.4

A.3 Datasheet of IGBT

Technische Information / technical information IGBT-Module IGBT-modules FZ600R12KE4												
<p>62mm C-Serien Modul mit Trench/Fieldstopp IGBT4 und Emitter Controlled 4 Diode 62mm C-Series module with Trench/Fieldstop IGBT4 and Emitter Controlled 4 diode</p>												
Vorläufige Daten / preliminary data												
 Typical Appearance		$V_{CES} = 1200V$ $I_C \text{ nom} = 600A / I_{CRM} = 1200A$										
Typische Anwendungen <ul style="list-style-type: none"> Hochleistungsumrichter Motorantriebe USV-Systeme Windgeneratoren 	Typical Applications <ul style="list-style-type: none"> High Power Converters Motor Drives UPS Systems Wind Turbines 	Electrical Features <ul style="list-style-type: none"> Extended Operation Temperature $T_{VJ, op}$ Low Switching Losses Unbeatable Robustness $V_{CE(on)}$ with positive Temperature Coefficient Low $V_{CE(on)}$ 										
Elektrische Eigenschaften <ul style="list-style-type: none"> Erweiterte Sperrschichttemperatur $T_{VJ, op}$ Niedrige Schaltverluste Sehr große Robustheit $V_{CE(on)}$ mit positivem Temperaturkoeffizienten niedriges $V_{CE(on)}$ 	Mechanische Eigenschaften <ul style="list-style-type: none"> 4kV AC 1min Isolationsfestigkeit Gehäuse mit CTI > 400 Große Luft- und Kriechstrecken Isolierte Bodenplatte Standardgehäuse 	Mechanical Features <ul style="list-style-type: none"> 4kV AC 1min Insulation Package with CTI > 400 High Creepage and Clearance Distances Isolated Base Plate Standard Housing 										
Module Label Code Barcode Code 128  Sample 0000012345600000000000												
Content of the Code <table> <tr> <td>Module Serial Number</td> <td>Digit 1 - 5</td> </tr> <tr> <td>Module Material Number</td> <td>6 - 11</td> </tr> <tr> <td>Production Order Number</td> <td>12 - 19</td> </tr> <tr> <td>Datecode (Production Year)</td> <td>20 - 21</td> </tr> <tr> <td>Datecode (Production Week)</td> <td>22 - 23</td> </tr> </table>			Module Serial Number	Digit 1 - 5	Module Material Number	6 - 11	Production Order Number	12 - 19	Datecode (Production Year)	20 - 21	Datecode (Production Week)	22 - 23
Module Serial Number	Digit 1 - 5											
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Datecode (Production Week)	22 - 23											
prepared by: MK approved by: WR	date of publication: 2009-08-07 revision: 2.1	material no: 31516 UL approved (E83335)										

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Figure A-7a Datasheet of FZ600R12KE4 IGBT

Technische Information / technical information		 infineon					
IGBT-Module IGBT-modules		Vorläufige Daten preliminary data					
IGBT-Wechselrichter / IGBT-inverter Höchstzulässige Werte / maximum rated values							
Kollektor-Emitter-Spannung collector-emitter voltage	T _{vj} = 25°C	V _{CES}	1200	V			
Kollektor-Dauergleichstrom DC-collector current	T _C = 100°C, T _{vj} = 175°C	I _C	600	A			
Periodischer Kollektor Spitzstrom repetitive peak collector current	t _P = 1 ms	I _{CRM}	1200	A			
Gesamt-Verlustleistung total power dissipation	T _C = 25°C, T _{vj} = 175°C	P _{tot}	3000	W			
Gate-Emitter-Spitzenspannung gate-emitter peak voltage		V _{GES}	+/-20	V			
Charakteristische Werte / characteristic values							
Kollektor-Emitter Sättigungsspannung collector-emitter saturation voltage	I _C = 600 A, V _{GE} = 15 V I _C = 600 A, V _{GE} = 15 V I _C = 600 A, V _{GE} = 15 V	T _{vj} = 25°C T _{vj} = 125°C T _{vj} = 150°C	V _{CE(sat)}	1.75 2.00 2.05			
Gate-Schwellenspannung gate threshold voltage	I _C = 23,0 mA, V _{CE} = V _{GE} , T _{vj} = 25°C	V _{GEth}	5,2	5,8			
Gateladung gate charge	V _{GE} = -15 V ... +15 V	Q _G	5,80	μC			
Innerer Gatewiderstand internal gate resistor	T _{vj} = 25°C	R _{Gint}	1,3	Ω			
Eingangskapazität input capacitance	f = 1 MHz, T _{vj} = 25°C, V _{CE} = 25 V, V _{GE} = 0 V	C _{iss}	42,0	nF			
Rückwirkungskapazität reverse transfer capacitance	f = 1 MHz, T _{vj} = 25°C, V _{CE} = 25 V, V _{GE} = 0 V	C _{res}	1,70	nF			
Kollektor-Emitter Reststrom collector-emitter cut-off current	V _{CE} = 1200 V, V _{GE} = 0 V, T _{vj} = 25°C	I _{CES}		5,0			
Gate-Emitter Reststrom gate-emitter leakage current	V _{CE} = 0 V, V _{GE} = 20 V, T _{vj} = 25°C	I _{GES}		400			
Einschaltverzögerungszeit (ind. Last) turn-on delay time (inductive load)	I _C = 600 A, V _{CE} = 600 V V _{GE} = ±15 V R _{Gon} = 1,2 Ω	T _{vj} = 25°C T _{vj} = 125°C T _{vj} = 150°C	t _{on}	0,24 0,25 0,26			
Anstiegszeit (induktive Last) rise time (inductive load)	I _C = 600 A, V _{CE} = 600 V V _{GE} = ±15 V R _{Gon} = 1,2 Ω	T _{vj} = 25°C T _{vj} = 125°C T _{vj} = 150°C	t	0,09 0,10 0,11			
Abschaltverzögerungszeit (ind. Last) turn-off delay time (inductive load)	I _C = 600 A, V _{CE} = 600 V V _{GE} = ±15 V R _{Got} = 1,2 Ω	T _{vj} = 25°C T _{vj} = 125°C T _{vj} = 150°C	t _{off}	0,61 0,64 0,66			
Fallzeit (induktive Last) fall time (inductive load)	I _C = 600 A, V _{CE} = 600 V V _{GE} = ±15 V R _{Got} = 1,2 Ω	T _{vj} = 25°C T _{vj} = 125°C T _{vj} = 150°C	t _f	0,10 0,14 0,15			
Einschaltverlustenergie pro Puls turn-on energy loss per pulse	I _C = 600 A, V _{CE} = 600 V, L _S = 60 nH V _{GE} = ±15 V, dI/dt = 5500 A/μs (T _{vj} =150°C) R _{Gon} = 1,2 Ω	T _{vj} = 25°C T _{vj} = 125°C T _{vj} = 150°C	E _{on}	35,0 50,0 55,0			
Abschaltverlustenergie pro Puls turn-off energy loss per pulse	I _C = 600 A, V _{CE} = 600 V, L _S = 60 nH V _{GE} = ±15 V, dI/dt = 3500 V/μs (T _{vj} =150°C) R _{Got} = 1,2 Ω	T _{vj} = 25°C T _{vj} = 125°C T _{vj} = 150°C	E _{off}	50,0 75,0 80,0			
Kurzschlussverhalten SC data	V _{GE} ≤ 15 V, V _{CC} = 800 V V _{CES(max)} = V _{CES} - L _{CE} · dI/dt	t _P ≤ 10 μs, T _{vj} = 150°C	I _{SC}	2400			
Innerer Wärmewiderstand thermal resistance, junction to case	pro IGBT / per IGBT		R _{thJC}	0,05			
Übergangs-Wärmewiderstand thermal resistance, case to heatsink	pro IGBT / per IGBT λ _{Pass} = 1 W/(m·K) / λ _{grease} = 1 W/(m·K)		R _{thCH}	0,017			
prepared by: MK	date of publication: 2009-08-07						
approved by: WR	revision: 2.1						

Figure A-7b Datasheet of FZ600R12KE4 IGBT

Technische Information / technical information IGBT-Module IGBT-modules							
		Vorläufige Daten preliminary data					
Diode-Wechselrichter / diode-inverter Höchstzulässige Werte / maximum rated values							
Periodische Spitzensperrspannung repetitive peak reverse voltage	$T_{vj} = 25^\circ\text{C}$	V_{RRM}	1200	V			
Dauergleichstrom DC forward current	I_F	600		A			
Periodischer Spitzenstrom repetitive peak forward current	$t_P = 1 \text{ ms}$	I_{FRM}	1200	A			
Grenzlastintegral Pt - value	$V_R = 0 \text{ V}, t_P = 10 \text{ ms}, T_{vj} = 125^\circ\text{C}$ $V_R = 0 \text{ V}, t_P = 10 \text{ ms}, T_{vj} = 150^\circ\text{C}$	P_t	51000 49000	A ² s A ² s			
Charakteristische Werte / characteristic values							
Durchlassspannung forward voltage	$I_F = 600 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 600 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 600 \text{ A}, V_{GE} = 0 \text{ V}$	$T_{vj} = 25^\circ\text{C}$ $T_{vj} = 125^\circ\text{C}$ $T_{vj} = 150^\circ\text{C}$	V_F	1,80 1,75 1,70 V V V			
Rückstromspitze peak reverse recovery current	$I_F = 600 \text{ A}, - dI/dt = 5500 \text{ A}/\mu\text{s} (T_{vj}=150^\circ\text{C})$ $V_R = 600 \text{ V}$ $V_{GE} = -15 \text{ V}$	$T_{vj} = 25^\circ\text{C}$ $T_{vj} = 125^\circ\text{C}$ $T_{vj} = 150^\circ\text{C}$	I_{RM}	440 560 590 A A A			
Sperrverzögerungsladung recovered charge	$I_F = 600 \text{ A}, - dI/dt = 5500 \text{ A}/\mu\text{s} (T_{vj}=150^\circ\text{C})$ $V_R = 600 \text{ V}$ $V_{GE} = -15 \text{ V}$	$T_{vj} = 25^\circ\text{C}$ $T_{vj} = 125^\circ\text{C}$ $T_{vj} = 150^\circ\text{C}$	Q	55,0 100 115 μC μC μC			
Abschaltenergie pro Puls reverse recovery energy	$I_F = 600 \text{ A}, - dI/dt = 5500 \text{ A}/\mu\text{s} (T_{vj}=150^\circ\text{C})$ $V_R = 600 \text{ V}$ $V_{GE} = -15 \text{ V}$	$T_{vj} = 25^\circ\text{C}$ $T_{vj} = 125^\circ\text{C}$ $T_{vj} = 150^\circ\text{C}$	E_{rcs}	27,0 52,0 60,0 mJ mJ mJ			
Innerer Wärmewiderstand thermal resistance, junction to case	pro Diode / per diode	R_{JC}		0,07 K/W			
Übergangs-Wärmewiderstand thermal resistance, case to heatsink	pro Diode / per diode $\lambda_{Paste} = 1 \text{ W}/(\text{m}\cdot\text{K}) / \lambda_{Gresse} = 1 \text{ W}/(\text{m}\cdot\text{K})$	R_{CH}	0,024	K/W			
prepared by: MK		date of publication: 2009-08-07					
approved by: WR		revision: 2.1					

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Figure A-7c Datasheet of FZ600R12KE4 IGBT

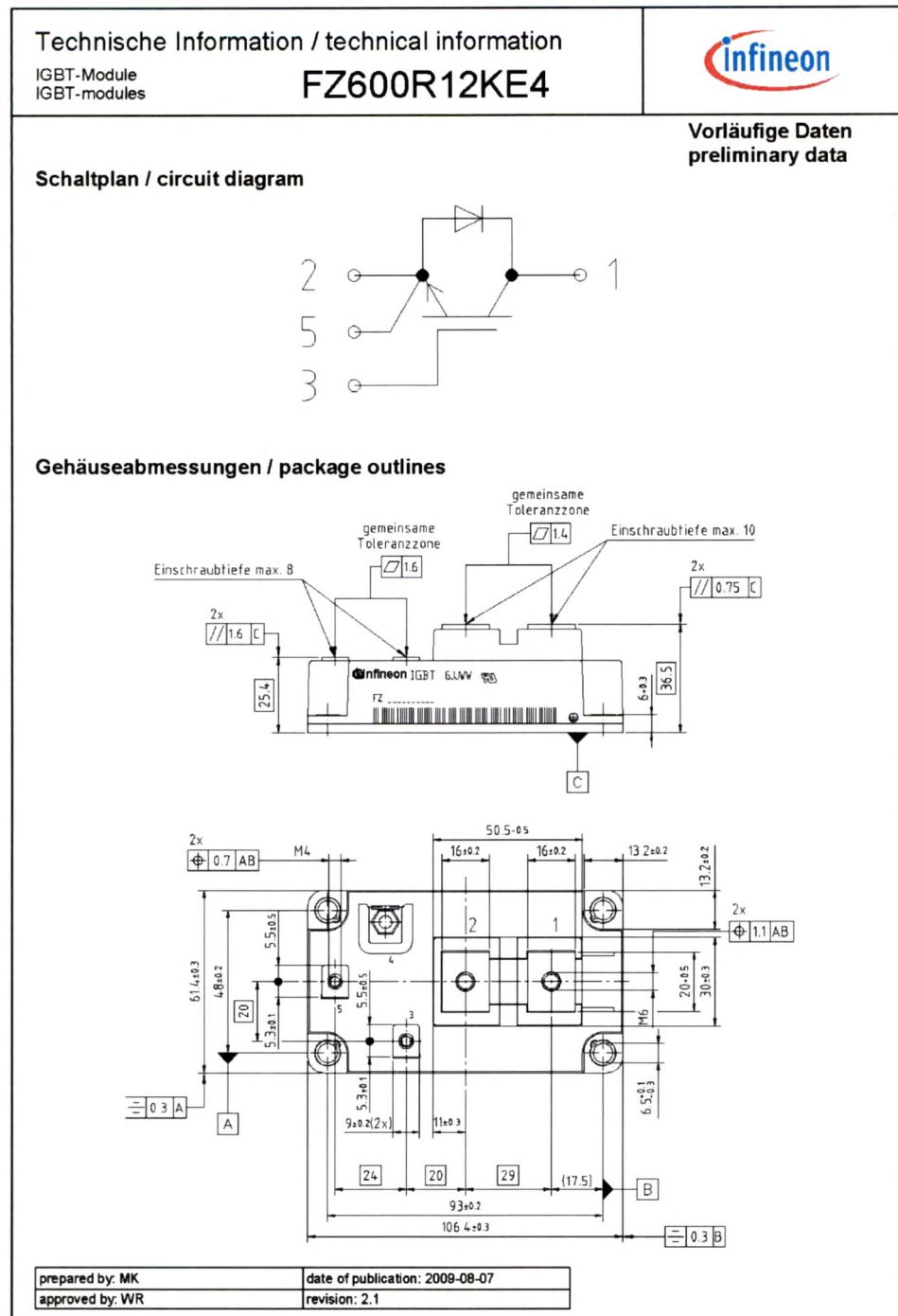


Figure A-7d Datasheet of FZ600R12KE4 IGBT